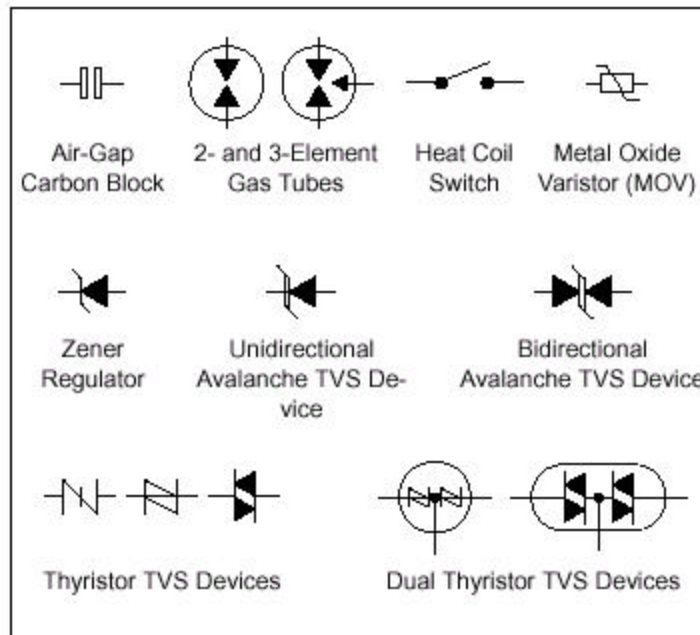


# A Unique Approach to TVS Characterization

A Technical Report Prepared for

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Courtesy of ON Semiconductor Zener/TVS Device Data Book

## **Presented by**

Steven Clauter, Design and Product Engineer  
Integrated Technology Corporation  
[steve@inttechcorp.com](mailto:steve@inttechcorp.com)

Larry Walker, Manager of the Discrete Evaluation Lab  
ON Semiconductor Corporation  
[larry.walker@onsemi.com](mailto:larry.walker@onsemi.com)

# **A Unique Approach to TVS Characterization**

## **Abstract**

In real-world conditions, the occurrence of a plurality of transient voltages is capable of dissipating significant power in circuit protection devices. In order to understand how Transient Voltage Suppressors, TVS, devices perform up to their rated power, techniques and equipment have been developed to characterize the effects of multiple industry-standard pulses being applied to TVS devices under controlled and monitored conditions. This study defines and demonstrates the TVS clamping voltage shifting that occurs during and immediately after transients are applied. It is envisioned that manufacturers of TVS devices, and circuit designers who use these devices, will find this information useful in increasing the level of transient voltage protection.

## **A. Background / Introduction**

As electronic products find broader applications, the need to protect becomes ever more important due to our dependence on maintaining proper circuit operation and data integrity. Generally, the push is for higher speed devices, which pushes the operating voltages way down resulting in devices ever more sensitive to electrical overstress conditions. Although transient disturbances can corrupt data on a temporary basis, Transient Voltage Suppressor, or TVS, devices main use is to prevent or at least limit costly permanent physical damage of electronic circuitry. In order to improve transient protection in both existing and new applications, a better understanding of TVS characteristics would be beneficial. This study will address a unique and useful method of characterization applicable to TVS protection devices of all kinds. In particular, a case study of several silicon TVS devices will be presented.

The market for TVS devices of all kinds is expected to grow at a compound annual rate of 5.7% in the period from 2000 to 2007. “The unbundling of utility operating units has diminished customer confidence in the industry’s ability to deliver reliable power. At the same time, customer downtime costs are rising and power quality is becoming a critical concern. Customers want assurance that they’ll receive high-quality power.”<sup>1</sup> With this in mind, the TVS market would be expected to have the following components:

- Increased Competition
- Pressure for Lower Prices
- Enhanced Performance
- Decreasing Package Size
- Integrated Transient Protection
- New Products

To deal with these market pressures, it is even more important to fully understand how to analyze TVS devices under meaningful current surge conditions utilizing new methods to duplicate various real-world situations.

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<sup>1</sup> Sara M. Bradford, “Market Trends in Transient Protection, Power Conditioning, and Batteries”, Power Quality, January 2002

This table shows a number of the many different standards are used to simulate real-world transient events in different applications.

Standard	Voltage	Waveform	Current	Waveform	Application
IEEE-472 ANSI C37 90.1 IEC TC 102D IEC 255 IEC TC 41	4,500V 2,500V 6,000V 5,000V 1, 2.5 kV	10/1000 uS 1.25MHz / 6 uS 1.2/50 uS	17A   12 A 25 A		Protective relays Static relays Remote-control receivers Static relays Static relays
IEC 801-4, IEC 61000-4-4  ANSI C62.41 CAT. B CAT. B CAT. C CCITT IX K17 K20 K15 FTZ 4391 tv1 (Gmy)	5,000V 5,000V 4,000V 6,000V 6,000V 6,000V 3 - 5 kV 2,500V	1.2 / 50 uS 0.5 uS / 100 KHz 5 / 50 nS 1.2 / 50 uS 5 uS / 100 KHz 5 uS / 100 KHz 10 / 700 uS 100 / 700 uS 10 / 700 uS	3,000 A   3,000 A 500 A 200 A	8 / 20 uS   8 / 20 uS	Industrial process control  LV ac power circuits  Repeaters  Telephone / microphone
FCC Sec. 86.302 PTT 692.01 (Swiss) EIA PM-1361  UL-4978	2,500V 4,000V 2,500V 1,000V 1,500V 1,000V	2 / 10 uS 1.0 / 50 uS 2 / 10 uS 10 / 1000 uS 10 / 1000 uS 10 / 1000 uS	1,000 A  1,000 A 200 A 400 A 10 A	2 / 10 uS  10 / 1000 uS 10 / 1000 uS	Telecom power line Telecom exchange Telecom terminals DP interface  Data communication
UL-1459 MIL-STD.704A  MIL-STD704D MILSTD-1275 MIL-STD1757 DODSTD-1399,Sec.300 440V 115V	50V 425V 600-200V 100V 32V 1,000 KV/uS 2,500V 1,000V	45 nS 30 nS 10 - 50 uS 50 nS 200 nS 1.2 / 50 uS 1.2 / 50 uS 1.2 / 50 uS	29 Vdc 270 Vac    200 kA 400 Vac 115 Vac	      200 kA 500 A 200 A	Std. telephone equipment Aircraft electrical power  Military vehicles  Aerospace vehicles Shipboard ac power

Source: "AJTVS - The Forgotten Component In Circuit Design" by David W. Hutchins  
Published in EMC Test & Design, March/April 1992

As can be seen from the table, identifying the transient events and standards to be used can be a complex task. Plus the standards are subject to being updated and expanded as new applications are considered. For example, early in the electronics industry, most transients were generated from external sources such as lightning and power line switching. In current times, with the advent of switching power supplies, battery operation and redundant/hot swap equipment over 60% of transient events are now generated locally or even internally.

The automotive industry is presenting an especially challenging market for transient protection and certainly almost all transients can be considered locally generated. Initially, the Load Dump standard was developed to handle the transients due to the switching of increased electrical loads present in today's cars. In the near future as the electrical loads continue to grow, 14/42 volt dual voltage systems will soon be presenting even new transient conditions to be considered in all automotive designs.

“Increasing electrical power consumption is straining the existing 12-V supply system of current vehicles. At some point in the not-too-distant future, manufacturers will have to change to a higher voltage to support improved emissions, safety, and new vehicle options. With the increased growth in vehicle loads (4%/year for the past two decades and about 100 W per year for the last five years)...”<sup>2</sup>

With all these items in mind, the need for a very flexible current surge tester is evident.

## **B. The Scope of this Study**

The goal of this study is to utilize the standardized waveforms and adapt them to provide even more information by analyzing the shifting in the TVS clamping voltage. As previously stated, although silicon TVS are presented, the concepts are applicable to all types of TVS devices in general, both active and passive. Adapting the standardized current waveforms involve digitally combining standard current waveforms and biasing the TVS devices with programmable currents before and after the transient pulse. The voltage across the TVS is then digitally stored and analyzed. While the method described could generate arbitrary current waveforms up to several hundred amperes, industry-standard waveforms will be used for the bulk of this effort.

At this point it would be appropriate to address why current transients are used in this study instead of voltage transients. Configuring the TVS in a shunt protection network, it is basically either off in normal operation or it turns on during the transient event. Although the initial transient may be either voltage or current externally, the TVS's performance is based on its transient current carrying capacity and its ability to clamp its terminal voltage within specified limits. The key design specifications for any TVS device are also all current-based as shown:

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<sup>2</sup> Randy Frank, Tim Phillips, Ryan Zahn, “Increases in future automobile voltages will directly and indirectly affect semiconductor devices in every automotive electronic system.”, ON Semiconductor, SAE Convergence 2000: An Electronics Showcase

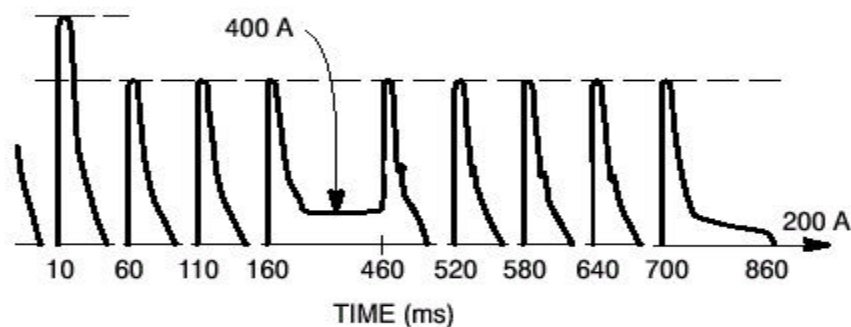
- $V_{RMW}$  - The maximum reverse working voltage where leakage current is measured, usually a few microamperes
- $V_{(BR)}$  - The avalanche voltage where a specified amount of reverse current is flowing, usually 1 to 100 milliamperes
- $V_{RSM}$  - The maximum reverse voltage, aka clamping voltage at the maximum rated current, usually 1 to 1000 amperes

“Transient voltage waveforms are commonly described in terms of a dual exponential wave ..... The standard chosen for power lines is a 1.2/50 ms voltage wave which **causes an 8/20 ms current wave**. Although the source of the most severe transients on telecom lines is the same as for power lines and lightning, the higher impedance per unit length of the telephone line stretches the waves as they propagate through the lines.”

“The 10/1000 ms wave approximates the worst case waveform observed on data and telecom lines. **TVS devices intended for this service are usually rated and characterized using a 10/1000 waveform**. The Bell South study revealed that the worst transient energy handled by primary protectors on lines entering a central office was equivalent to only 27 A peak of a 10/1000 wave. This level is considerably less than that required by secondary protectors in most of the standards in use today. This finding is particularly significant because the Bell South service area includes Central Florida, the region experiencing the highest lightning activity in the U.S.”<sup>3</sup> (emphasis added)

Finally by combining the standard current waveforms, worst case scenarios can be constructed consisting of a plurality of transient events. These current waveforms can then be accurately reproduced so that their effect on TVS devices can be studied.

Consider the following Severe Lightning Model:<sup>4</sup>

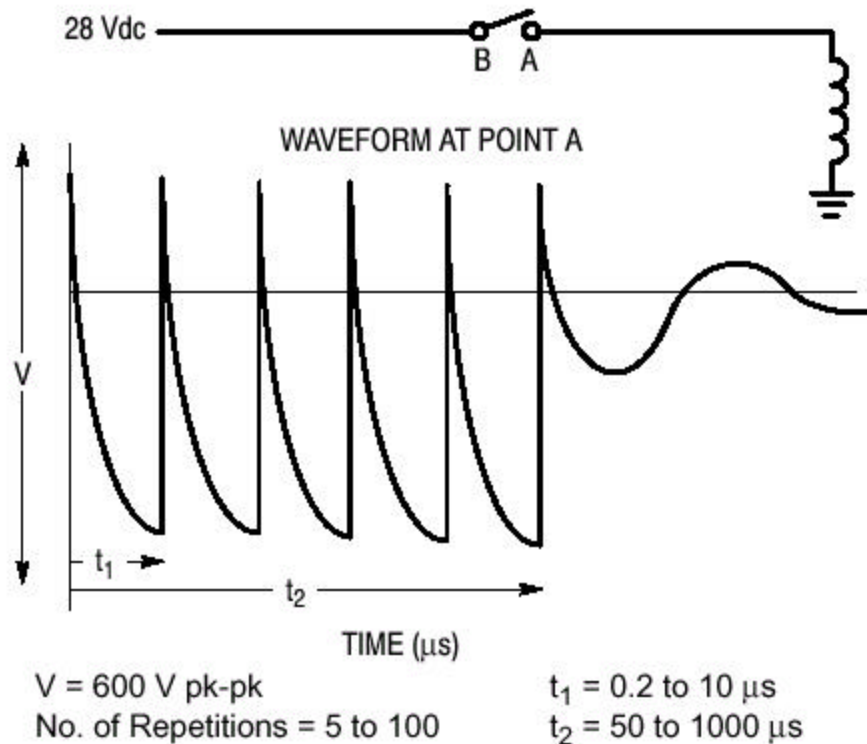


Depending on various conditions, continuing current may or may not be present in a lightning strike. A severe lightning model has also been created, which gives an indication of the strength which can be expected during worst case conditions at a point very near the strike location. The figure above shows this model. Note that continuing current is present at more than one interval, greatly exacerbating the damage which can be expected. A severe strike can be expected to ignite combustible materials.

<sup>3</sup> ON Semiconductor, “TVS/Zener Device” Databook, Rev2 2001, page 387.

<sup>4</sup> ON Semiconductor, “TVS/Zener Device” Databook, Rev2 2001, page 384.

Another example of multiple transient events is as follows:



“After characterizing electrical overstress on aircraft power buses, Boeing published **Document D6-16050** as shown.

The military has developed switching transient definitions within several specifications including:

- DOD-STD-1399** for shipboard
- MIL-STD-704** for aircraft
- MIL-STD-1275** for ground vehicles

The International Electrotechnical Commission (IEC) is now promoting their specification **IEC 801-4** throughout the European community. This describes an inductive switching transient voltage threat having 50 ns wide spikes with amplitudes from 2 kV to 4 kV occurring in 300 ms wide bursts.<sup>5</sup>

Besides these particular military specifications, many are application specific and functional tests exist. A supplier of transient voltage suppressor components will be expected to perform to a wide variety of them.<sup>6</sup>

The initial focus of this study will be the variation and shifting of reverse breakdown and clamping voltages due to absorbing transient energy. The availability of using a digital arbitrary waveform allows for measurements when one or more standard waveform transients are generated.

<sup>5</sup> O. M. Clark, “Transient Voltage Suppression (TVS),” 1989, page 7.

<sup>6</sup> ON Semiconductor, “TVS/Zener Device” Databook, Rev2 2001, page 386.

The first order effects and observations of this energy dissipation would involve:

- Increase in die temperature
- Stressing/Evaluation of die bonds
- Current sharing and/or channeling
- Thermal gradients across the die
- Thermal gradients from die to ambient via packaging
- Overall power dissipation capabilities

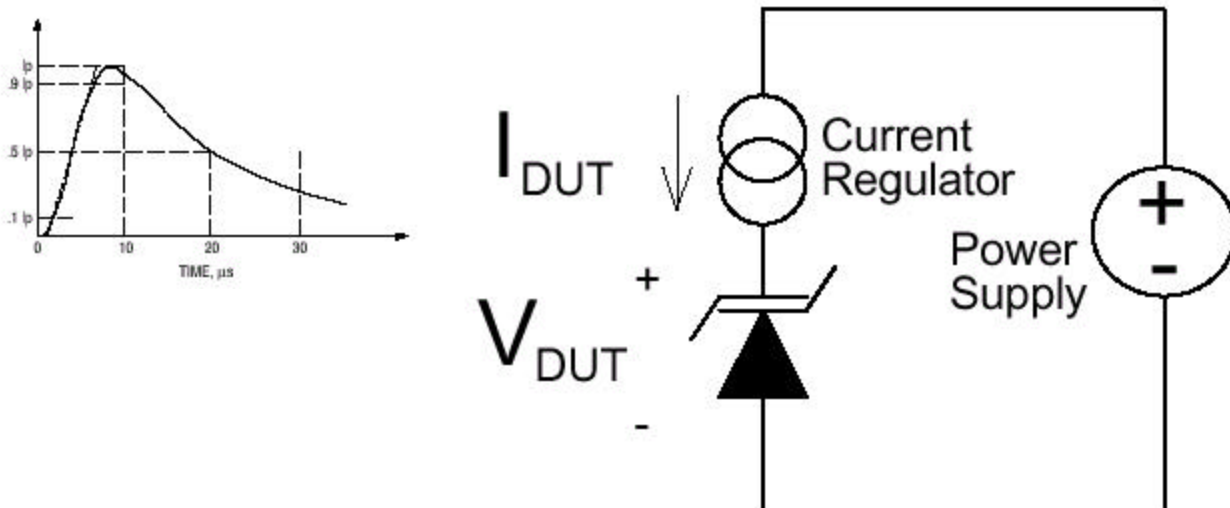
In general terms, as a result of these and subsequent studies, the following benefits could be expected:

- Improvements to silicon TVS device designs
- Advancement in packaging
- Qualifying silicon TVS devices to match particular applications
- Integrating TVS protection into ICs

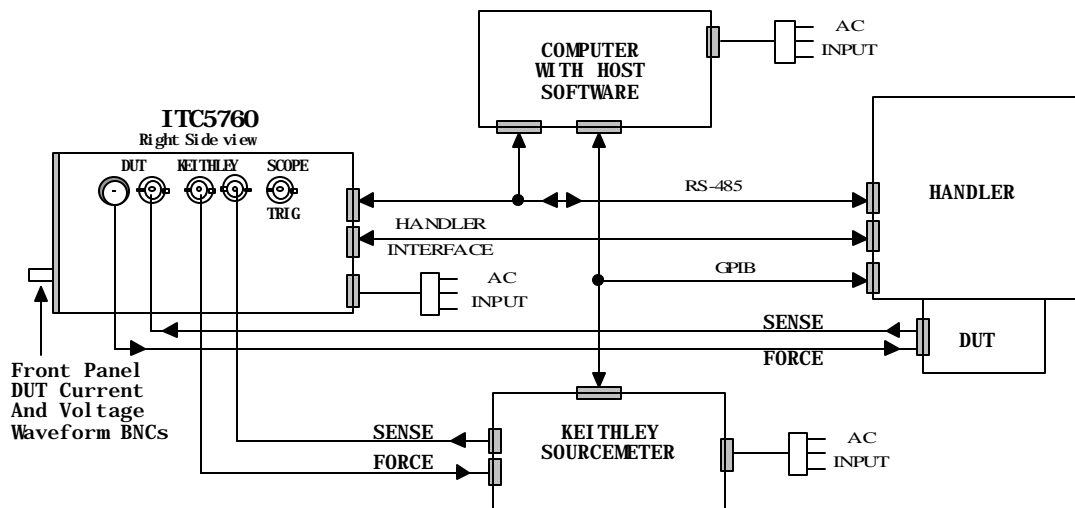
### C. The Method

A TVS test system, the ITC 5760, was developed by Integrated Technology Corporation to digitally generate the current waveforms, store the resulting TVS voltage data, and analyze test results. Conventional transient test systems have often used traditional RLC networks to generate the standard current waveforms. The ITC 5760 was designed with a programmable active current regulator to provide a wide range of accurate current waveforms up to 320 amperes and could be easily customized to generate almost any waveform. Waveforms can also be downloaded from Excel spreadsheet files.

The basic block diagram of the current loop used generate almost any current surge waveform is show below:



The main system Host software runs on a PC computer and provides a user interface to setup, run, and record all the tests. This software was written and compiled using the LabView Development Software Suite of tools provided by National Instruments. Once the operator has selected a particular test, this information is downloaded via a high speed RS-485 network to the ITC 5760 test station. The operator can then initiate testing. The resulting DUT voltage and current waveforms are digitized, returned to the PC via the RS-485 network, and displayed on the PC's user screen. In addition, a digital oscilloscope connects to the front panel BNCs and captures DUT voltage and current waveforms for correlation or other use. The Handler and Keithley Sourcemeter are not utilized with these transient tests but are used for DC testing such as leakage. The DUT is placed in the DUT test fixture as shown with force and sense connections.



The current waveforms used for testing were initially generated in Excel spreadsheets and then imported using one of the utility programs the ITC 5760 software provides. Each waveform can contain up to 1000 datapoints that can source from 10 milliamperes to 320 amperes of DUT current at a rate of 1uS to 100 uSec per datapoint. DUT voltages can be digitized and measured up to 400 Vdc.

## D. Test Results

Two different ON Semiconductor TVS devices were selected for testing in this study:

**1SMB75CAT3** Bidirectional 600 Watt Peak Power Zener TVS. SMT Plastic SMB

$V_{RMW}$ : 75 Volts at  $I_R = 5 \mu A$

$V_{(BR)}$ : 83.3 to 92.07 Volts at  $I_Z = 1 \text{ mA}$

$V_{(BR)}$ : 121 Volts MAX at  $I_Z = 4.9 \text{ A}$ , 10x1000 uSec Pulse Width at  $T_C = 30 \text{ deg C}$

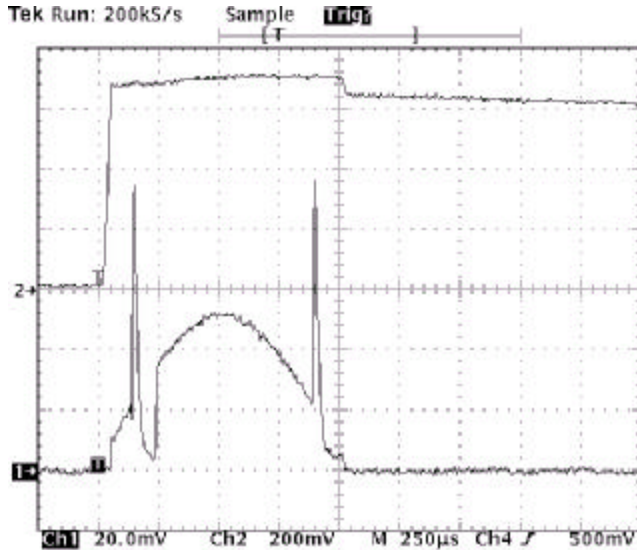
**MR2835S** Overvoltage Transient Suppressor, SMT Automotive System TVS

$V_{RMW}$ : 23 Volts at  $I_R = 5 \mu A$

$V_{(BR)}$ : 24 to 32 Volts at  $I_Z = 100 \text{ mA}$

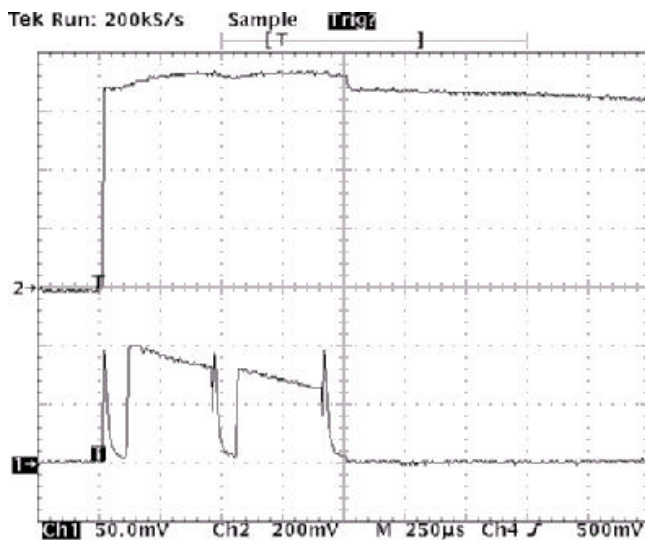
$V_{(BR)}$ : 40 Volts MAX at  $I_Z = 80 \text{ A}$ , 80 uSec Pulse Width at  $T_C = 85 \text{ deg C}$

The first DUT Current Waveform used is shown below is basically a combination of 2, 8x20 waveforms at the beginning and end of a 1 mSec Half Sine wave. In addition there are 1% current pedestals during the first and last 50 uSec of the waveform. Obviously many other current waveforms and test protocols could be utilized.



Waveform #1-2x8x20+1mSec Half Sine  
1SMB75CAT3 Waveforms  
Channel 1: DUT Current, 0.20A/div  
 $I = 0.96\text{A-peak}$   
Channel 2: DUT Voltage, 20V/div  
 $\Delta V = 71 - 68 = 3\text{V}$

Note how the voltage waveform rises during the testing due to the heating effects of the transients. The 8x20 transients contain far less total energy than the 1mSec half sine envelope. At these current levels the 8x20 transient effect on the DUT voltage is negligible.

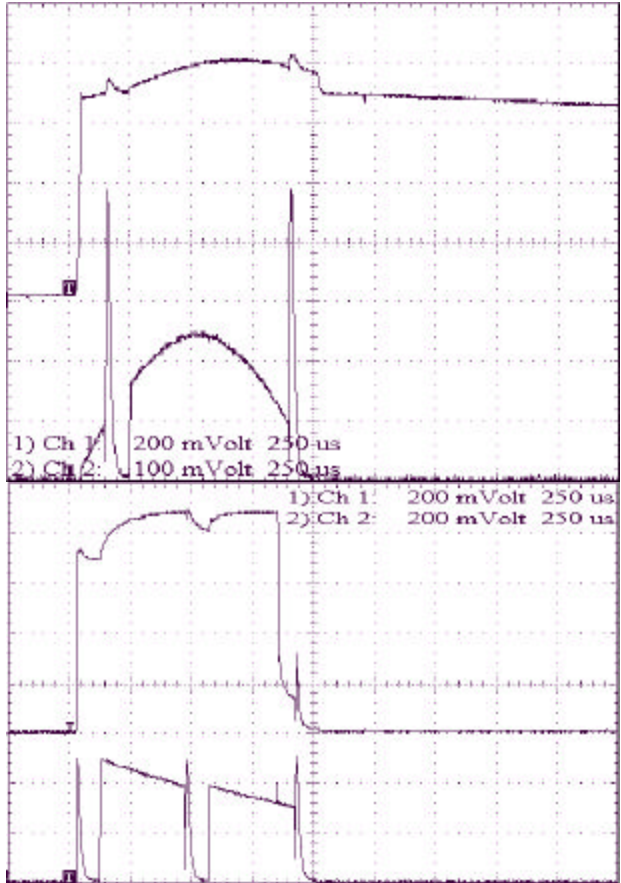


Waveform #2 – 3x8x20+10x1000  
1SMB75CAT3 Waveforms  
Channel 1: DUT Current, 0.50A/div  
 $I = 1.0\text{A-peak}$   
Channel 2: DUT Voltage, 20V/div  
 $\Delta V = 74 - 68 = 4\text{V}$

Note how the voltage waveform rises during the testing mainly due to the heating effects of the 10x1000 transient. Once again the 8x20 transients contain far less total energy than the 10x1000 envelope. At these current levels the 8x20 transient effect on the DUT voltage is negligible.

Now the current will be increased from 1 amp to 5 amps which is slightly beyond its maximum specified current limit of 4.9 amps. There should now be some visible effects of this higher current as follows:

- Shifting of Clamping Voltage during the 8x20 transients
- Thermal time constant will be visible
- Variation of Clamping Voltage due to current variation
- Maximum current limits with multiple transients

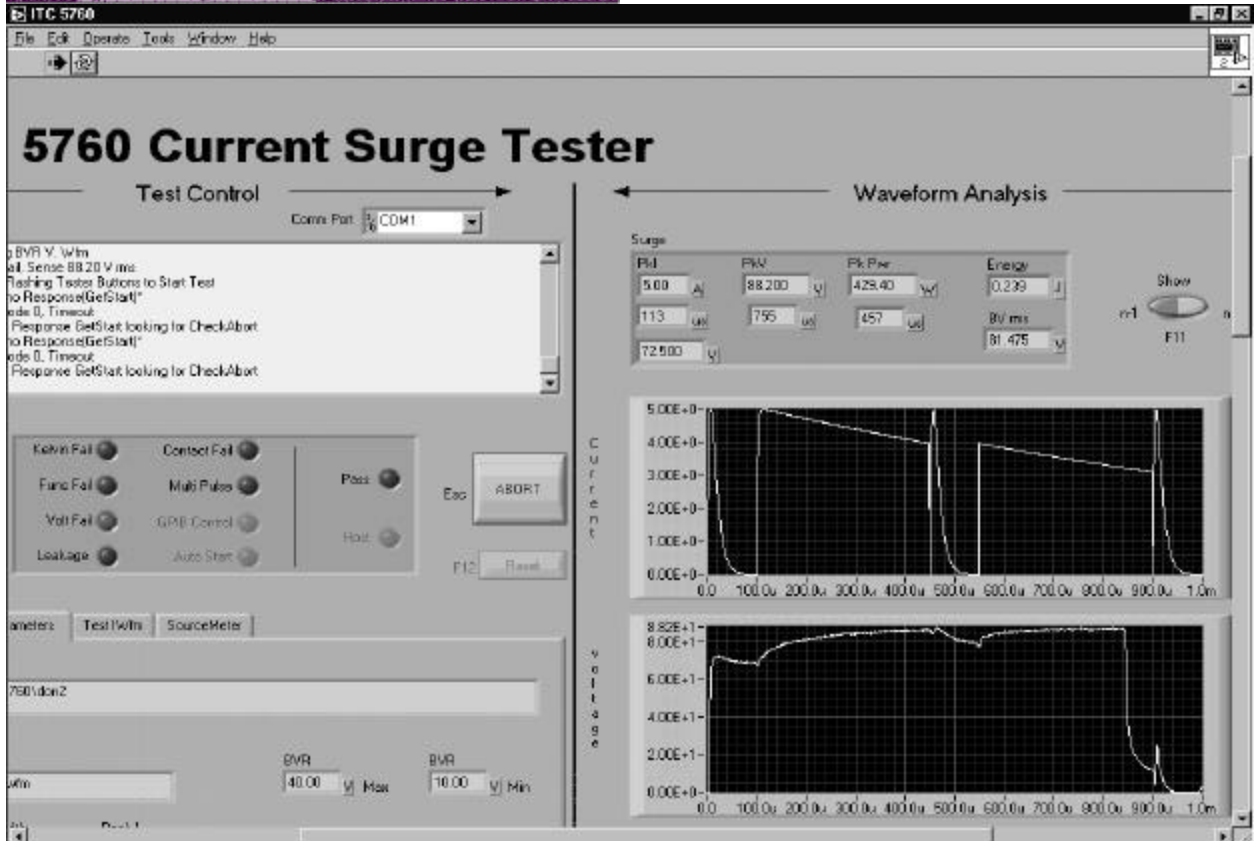


Waveform #3-2x8x20+1mSec Half Sine  
1SMB75CAT3 Waveforms

Channel 1: DUT Voltage, 20V/div  
Delta V = 84 – 70 = 14V

Channel 2: DUT Current, 1.0A/div  
I = 5.0A-peak

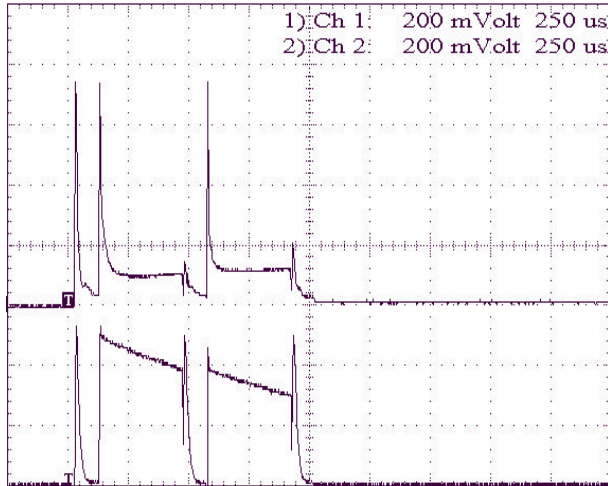
Note how the voltage waveform rises significantly during the 8x20 transient and how the second 8x20 has a higher clamping voltage. The voltage also shows a thermal phase shift with regard to the peak current.



Waveform #4 – 3x8x20+10x1000  
1SMB75CAT3 Waveforms

Channel 1: DUT Voltage, 20V/div  
Delta V = 88 – 73 = 15V,  
then **FAILURE**

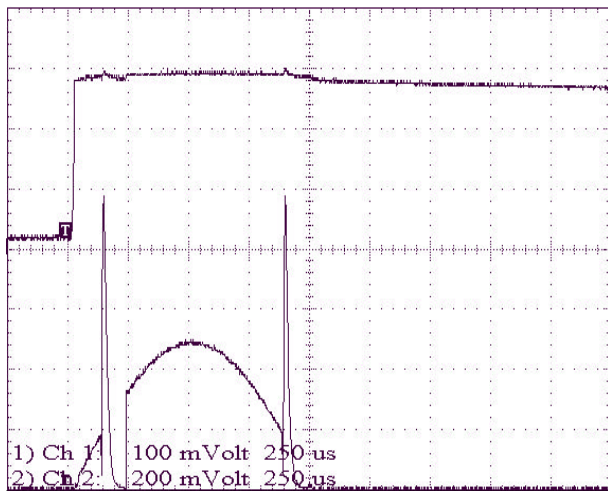
Channel 2: DUT Current, 2.0A/div  
**Failure at 880uSec.** Note how the DUT voltage drops suddenly while the current waveform remains unchanged. The PC screen is also shown below.



Waveform #5 – 3x8x20+10x1000  
 1SMB75CAT3 Waveforms  
 Channel 1: DUT Voltage, 20V/div  
**FAILURE**  
 Channel 2: DUT Current, 2.0A/div  
 $I = 5.0A\text{-peak}$

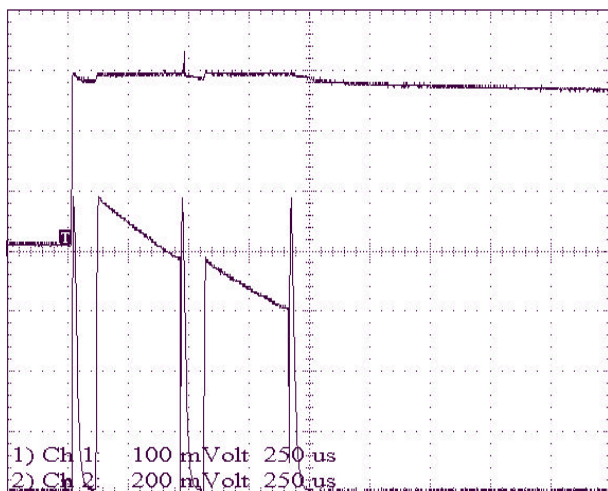
This is another surge with the part that just failed as shown in Waveform #4. At this point the DUT is low impedance as shown by this waveform. Note the voltage rises and then collapses at the point where the transient occurs.

The next phase of testing will use the MR3525S parts, higher current and lower voltage:



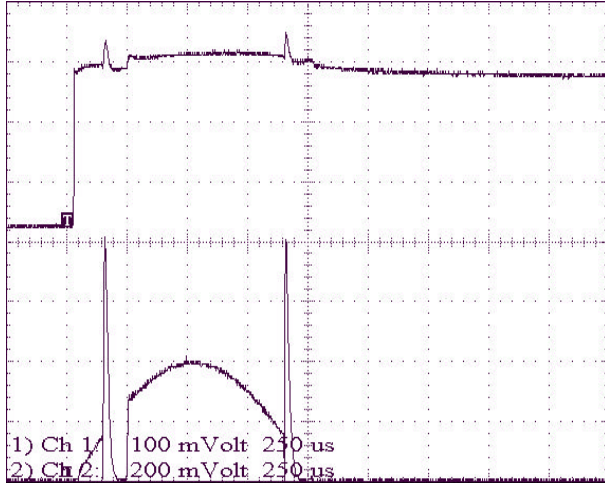
Waveform #6-2x8x20+1mSec Half Sine  
 MR3528S Waveforms  
 Channel 1: DUT Voltage, 10V/div  
 $\Delta V = 30 - 28 = 2V$   
 Channel 2: DUT Current, 2.0A/div  
 $I = 10A\text{-peak}$

Note how the voltage waveform rises during the testing due to the heating effects of the transients. At these current levels the 8x20 transient is barely visible.



Waveform #7 – 3x8x20+10x1000  
 MR2835S Waveforms  
 Channel 1: DUT Voltage, 10V/div  
 $\Delta V = 30 - 29 = 1V$   
 Channel 2: DUT Current, 2.0A/div  
 $I = 10A\text{-peak}$

Again the voltage waveform rises very little during the testing. At these current levels the 8x20 transient effect on the DUT voltage is also negligible.



Waveform #8 - 2x8x20+1mSec Half Sine

MR3528S Waveforms

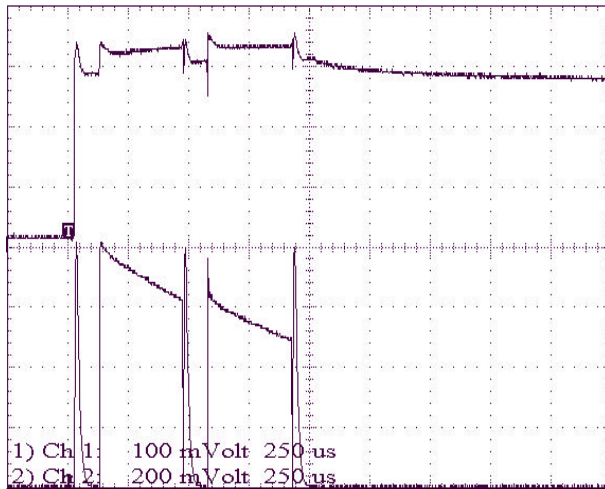
Channel 1: DUT Voltage, 10V/div

$$\Delta V = 35 - 33 = 2V$$

Channel 2: DUT Current, 20A/div

$$I = 80A\text{-peak}$$

At this point the 8x20 transients are visible although the voltage differential between the 2 transients is about the same as the 10A pulse.



Waveform #9 - 3x8x20+10x1000

MR3528S Waveforms

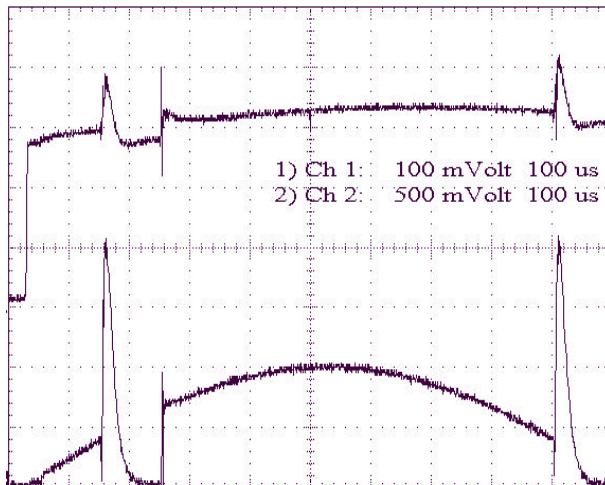
Channel 1: DUT Voltage, 10V/div

$$\Delta V = 36 - 34 = 2V$$

Channel 2: DUT Current, 20A/div

$$I = 80A\text{-peak}$$

Again the 8x20 transients are visible although the voltage differential between the 2 transients is about the same as the 10A pulse.



Waveform #10 - 2x8x20+1mSec Half Sine

MR3528S Waveforms

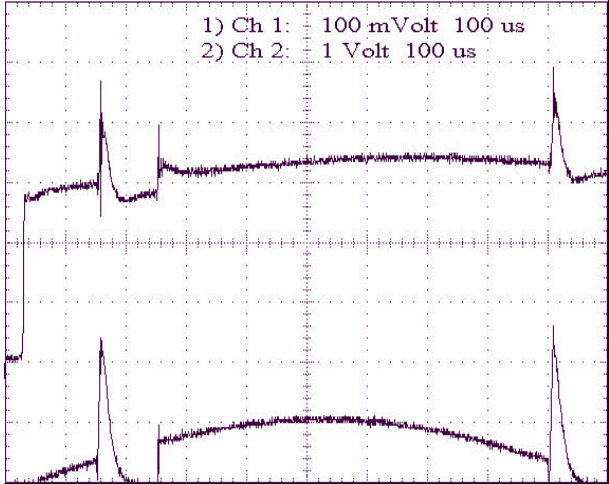
Channel 1: DUT Voltage, 10V/div

$$\Delta V = 42 - 38 = 4V$$

Channel 2: DUT Current, 50A/div

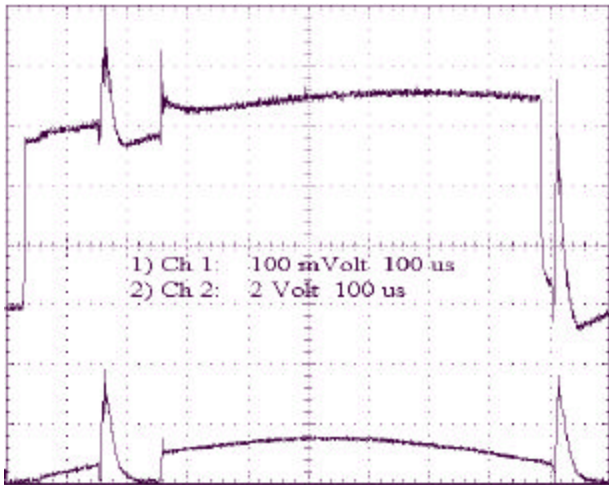
$$I = 200A\text{-peak}$$

The 8x20 transients are clearly visible and the voltage differential between the 2 transients has doubled to 4 volts indicative of higher die temperature and greater overall stress.



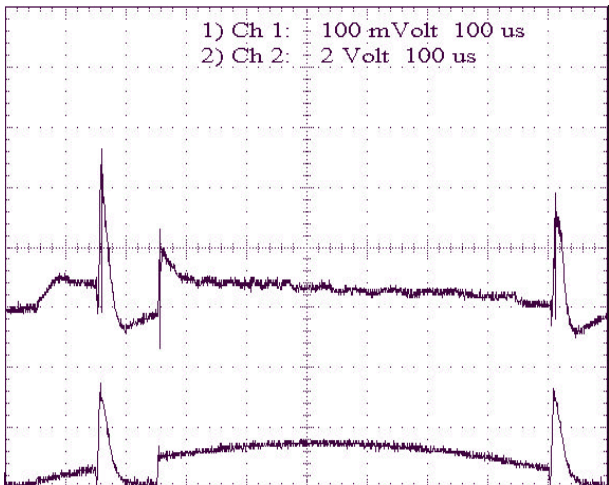
Waveform #11 – 3x8x20+10x1000  
MR3528S Waveforms  
Channel 1: DUT Voltage, 10V/div  
Delta V = 45 – 39 = 6V  
Channel 2: DUT Current, 100A/div  
I = 250A-peak

The 8x20 transients continue to push the clamping voltage higher with increased current. The voltage differential between the 2 transients has increased another 50% while the current has increased only 25%. It would appear that die temperature and overall stress is rising even higher.



Waveform #12 - 2x8x20+1mSec Half Sine  
MR3528S Waveforms  
Channel 1: DUT Voltage, 10V/div  
**FAILURE**

Channel 2: DUT Current, 200A/div  
I = 300A-peak  
**Failure at 880uSec.** Note how the DUT voltage drops suddenly while the current transient waveform remain unchanged.



Waveform #13 -2x8x20+1mSec Half Sine  
MR3528S Waveforms  
Channel 1: DUT Voltage, 10V/div  
**FAILURE**  
Channel 2: DUT Current, 2.0A/div  
I = 5.0A-peak

This is another current surge with the part that just failed as shown in Waveform #4. At this point the DUT is low impedance as shown by this waveform. Note the voltage rises and then collapses at the point where the current transient occurs.

## **E. Conclusions**

This study was admittedly a first step. Many other application-specific uses of these basic methods are envisioned. Although many issues were only briefly presented, some general conclusions should be of interest to all personnel involved in phases of TVS design and application.

Namely,

1. A flexible, programmable current surge tester can reveal and record a wide variety of important TVS device characteristics.
2. Both standard and customized current surges are useful. The ability to load and accurately reproduce standardized current pulses and import waveforms affords new opportunities in device evaluation.
3. The effects of multiple transients can be used to insure transient protection is adequate and relates well to real-world events.
4. One particular characteristic studied was the shifting of clamping voltage during multiple current transients. This shifting is an indication of die temperature and overall TVS stresses during transient conditions.
5. Measuring TVS operating voltages and surge currents plus the stresses they create can also be used to improve TVS device design, packaging, die attachment, reliability, life expectancy, and many other related TVS properties.